L Number	Hits	Search Text	DB	Time stamp
1	0	118/37.ccls. and (solder near3 wettable)	USPAT	2003/03/31 09:00
2	14	228/37.ccls. and (solder near3 wettable)	USPAT	2003/03/31 09:10
3	339	228/\$.ccls. and (solder near3 wettable)	USPAT	2003/03/31 09:10
4	230	228/36.ccls. or 228/36.ccls. or	USPAT	2003/03/31 09:11
		228/40.ccls.		
5	104	228/36.ccls. or 228/36.ccls. or	USPAT	2003/03/31 09:12
		228/40.ccls. and (solder near3 wettable)		
6	39	228/36.ccls. or 228/36.ccls. or	USOCR	2003/03/31 09:12
		228/40.ccls. and (solder near3 wettable)		

US-PAT-NO:

4614294

DOCUMENT-IDENTIFIER: US 4614294 A

TITLE: Apparatus for holding a part in a wave

soldering machine



An important feature of both embodiments of the present invention is that

the surface tension inherent in the surface of the solder 52 is utilized to

limit the depth of penetration of leads into the solder thereby preventing

solder from reaching the body of the IC device while tinning the leads. This

novel use of surface tension is effected by means of the pair of beveled

surfaces on either side of the lead to be tinned. It is important, of course,

that these beveled surfaces be made of a suitable material that is not wettable

by the solder 52.

228/3

US-PAT-NO:

4545520

DOCUMENT-IDENTIFIER: US 4545520 A

TITLE:

Method and system for soldering insulation

coated parts

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The pressure on the solder is set so that a sufficient quantity of solder flows into and fills the housings 66, 67 and 68 with solder streams having exposed surfaces that project slightly through the openings 76, 77 and 78. The channel housings are made of a non-solder wettable material, such as titanium, hence the edges of the solder streams will be repelled which, in conjunction with the normal meniscus effect, allows the top surfaces 79 (see FIG. 8) of the solder channel streams to rise above the level of the openings in the housings. It should be noted that the solder streams do not flow over the sides of the housings 66, 67 and 68.

5. An apparatus as set forth in claim 4 wherein the channel side plates are constructed of non-solder wettable material for confining the



US-PAT-NO:

4527731

DOCUMENT-IDENTIFIER: US 4527731 A

TITLE:

Method and apparatus for applying stripes

of solder to

articles

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More particularly, a solder stream of precise controllable width is

generated by impressing pressurized solder into an inclined chamber comprising

a channel having a pair of side walls of equal height. A bar is mounted within

the side walls to establish a solder stream bed, and the bar is provided with a

series of aligned longitudinally spaced holes through which the pressurized

solder is forced to form a series of contiguous jets. The jets merge to form a

solder stream that flows down the inclined channel. The side walls are

constructed of a non-solder wettable material so that there is a meniscus

effect between the edges of the solder stream and the top inner surfaces of the

side walls which in conjunction with the jets of solder form a swell of solder